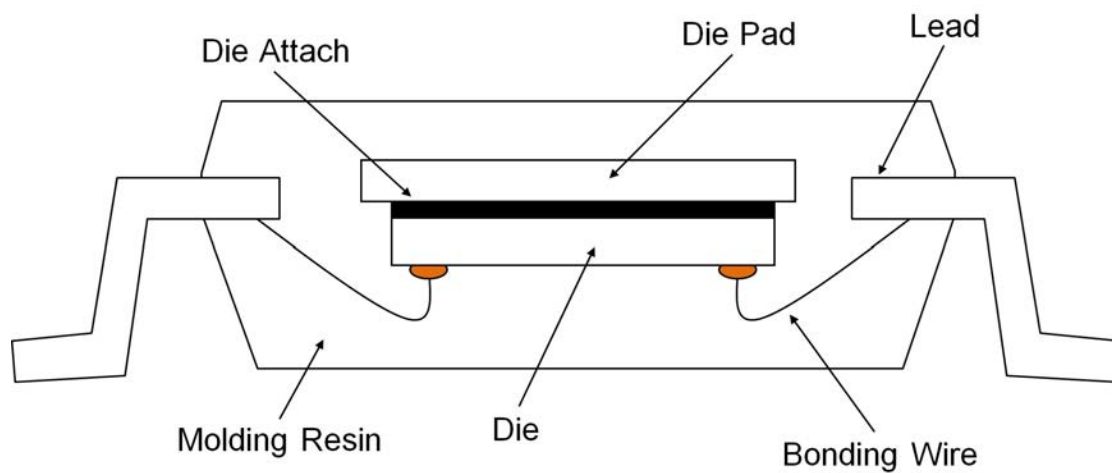


## 1. Package Information

|                    |          |
|--------------------|----------|
| Package Name       | SSOP5    |
| Type               | SOP      |
| Pin Count          | 5        |
| Package Weight [g] | 0.014    |
| Lead Finish        | Pure Tin |
| MSL                | Level1   |

## 2. Package Structure



### 3. Packing Specification

#### 3.1 Packing form, Quantity, PIN1 Orientation

|                   |       |           |
|-------------------|-------|-----------|
| Packing Form      |       | Tape&Reel |
| Packing Quantity  | [pcs] | 3,000     |
| PIN 1 Orientation |       | TL        |

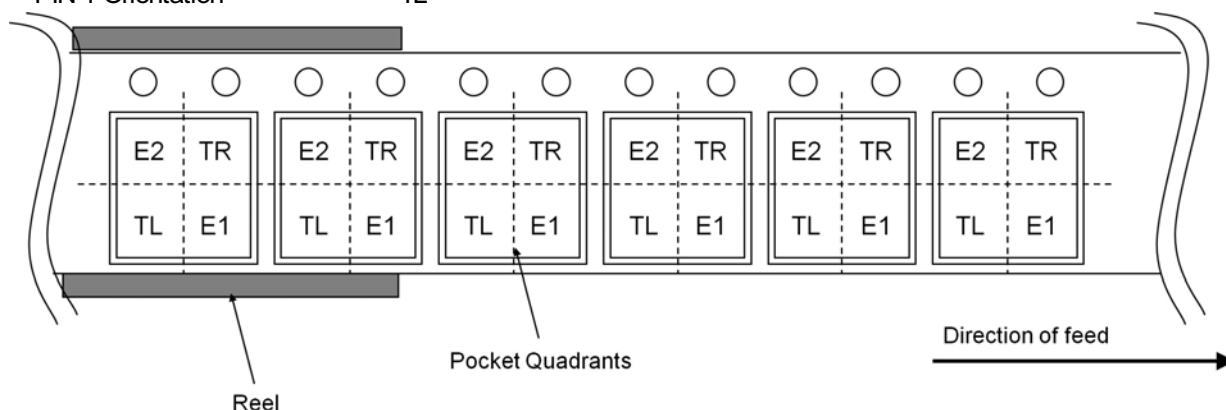


Fig.1 Quadrant Assignments for PIN 1 Orientation in Tape

E2 : PIN1 is placed to the top left corner.

TR : PIN1 is placed to the top right corner.

TL : PIN1 is placed to the lower left.

E1 : PIN1 is placed to the lower right.

Fig.1 PIN 1 Orientation in tape

#### 3.2 Use material

| Item                  | Material           |
|-----------------------|--------------------|
| Embossed carrier tape | PS                 |
| Cover tape            | PET+PE             |
| Reel                  | PS                 |
| Desiccant             | Clay               |
| Envelope              | Aluminum-laminated |
| Air cap               | -                  |
| Unit box              | Cardboard          |
| Shipping box          | Cardboard          |

#### 3.3 Leader specification

No component pockets are 400 mm or more.

#### 3.4 Trailer specification

No component pockets are 160 mm or more. Tape is free from reel.

#### 3.5 Peelback strength

Cover tape peelback strength is 0.2 N to 0.7 N.

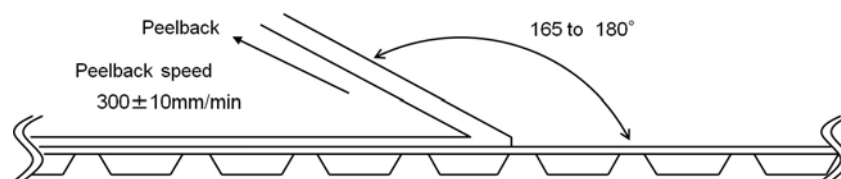


Fig. 2 Test method

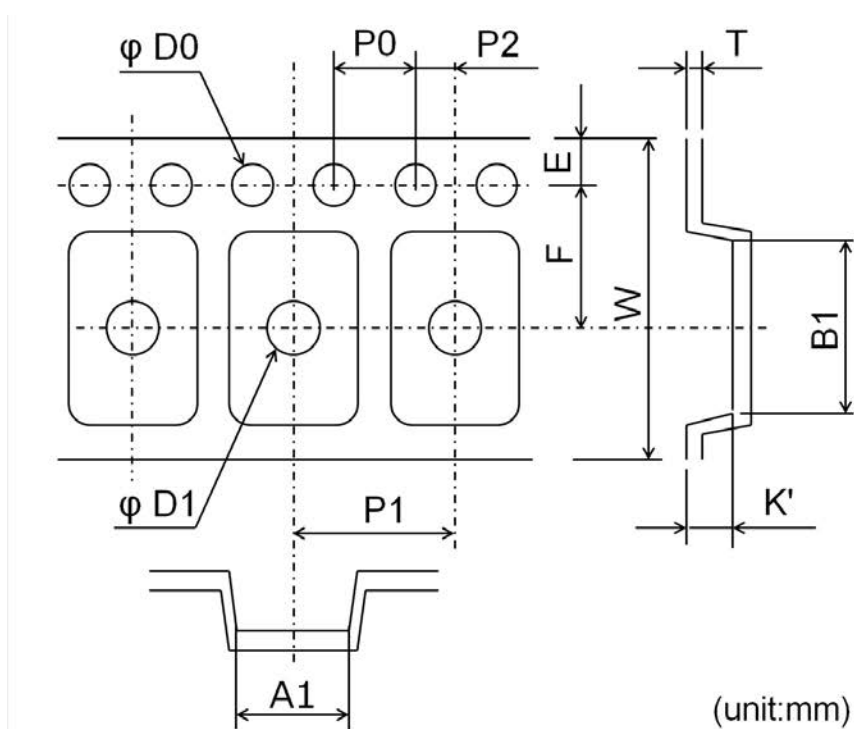
#### 3.6 Missing lcs

(1) No consecutive dropouts.

(2) A maximum 0.1 % of specified number of products in each packing may be missing.

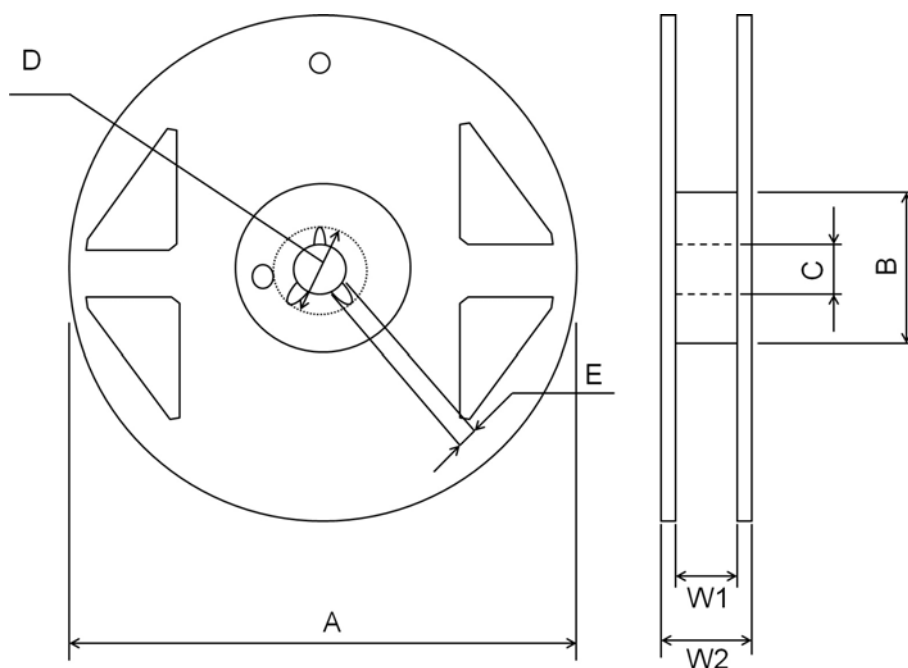
## 3.7 Tape and Reel Specification

## 3.7.1 Tape Dimension



|    | Tape Dimension | Tape Tolerance |
|----|----------------|----------------|
| A1 | 3.20           | ±0.1           |
| B1 | 3.10           | ±0.1           |
| D0 | φ1.5           | +0.1/-0        |
| D1 | φ1.1           | ±0.1           |
| E  | 1.75           | ±0.1           |
| F  | 3.50           | ±0.05          |
| K' | 1.30           | ±0.1           |
| P0 | 4.00           | ±0.1           |
| P1 | 4.00           | ±0.1           |
| P2 | 2.00           | ±0.1           |
| T  | 0.30           | ±0.05          |
| W  | 8.00           | ±0.3           |

## 3.7.2 Reel Dimension

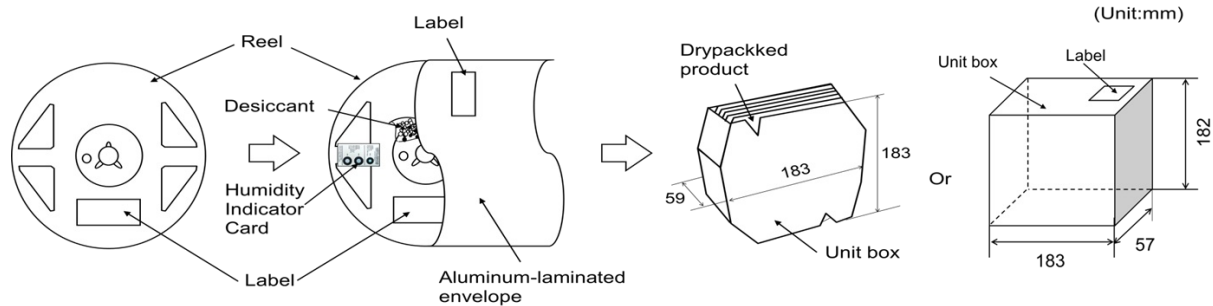


(unit:mm)

|    | Reel Dimension | Reel Tolerance |
|----|----------------|----------------|
| A  | 180            | +0/-1.5        |
| B  | 60             | +1.0/-0        |
| C  | 13             | ±0.2           |
| D  | 21             | ±0.8           |
| E  | 2              | ±0.5           |
| W1 | 9              | +1.0/-0        |
| W2 | 11.4           | ±1.0           |

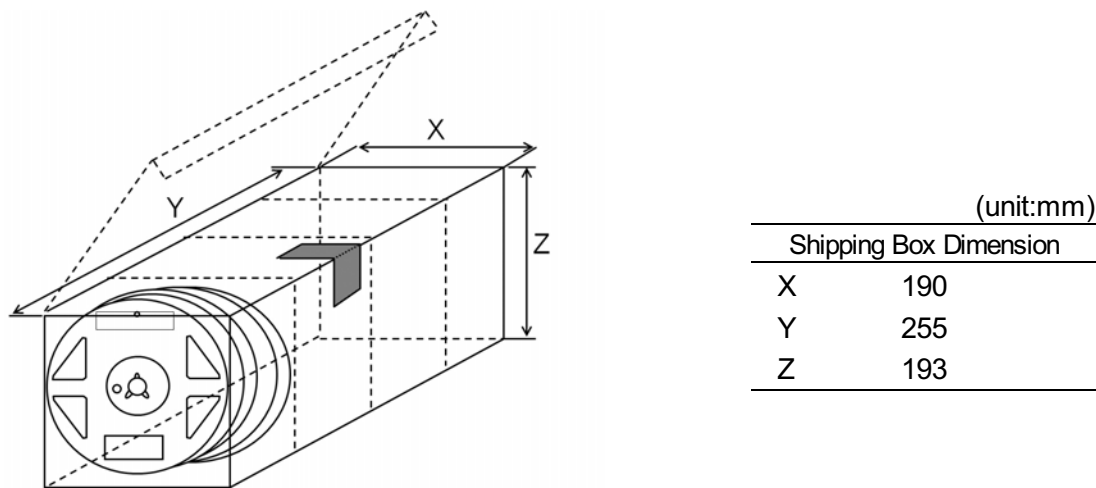
3.8 Packing Method

2 reel(s) or less per unit box



3.9 Packing Style

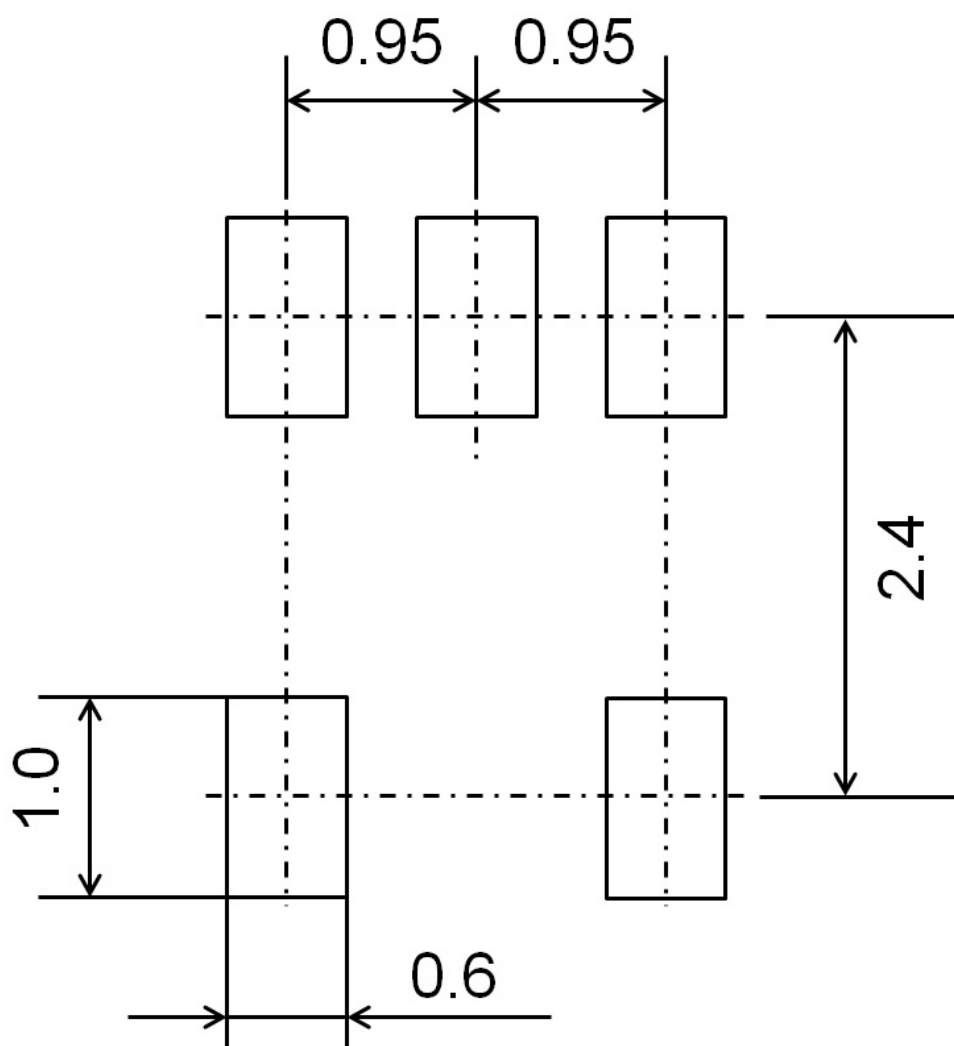
4 unit boxes or less per shipping box



3.10 Label Specification



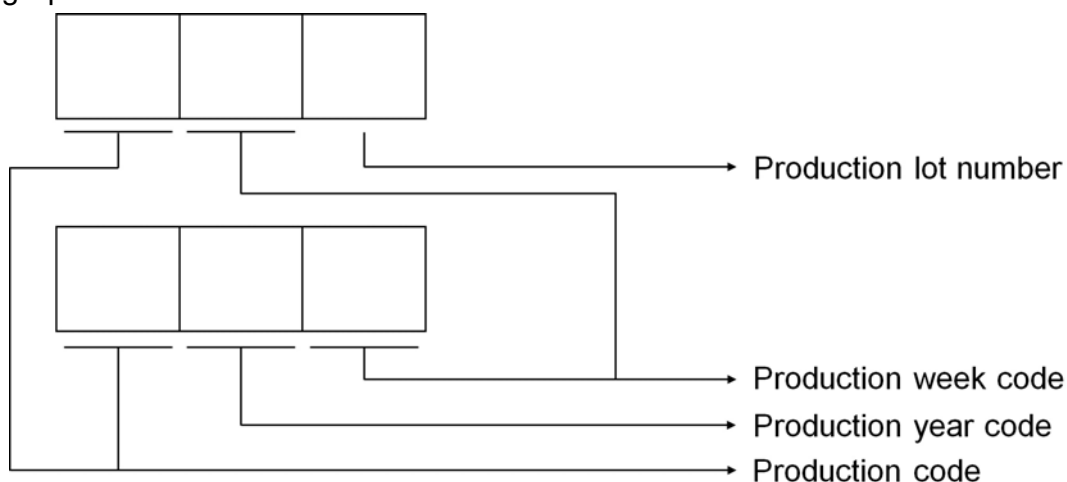
## 4. Footprint dimensions



(unit:mm)

In actual design, please optimize in accordance with the situation of your board design and soldering condition.

## 5. Marking Specification



## 6. Storage conditions

## 6.1 Storage environment

## Recommended storage conditions

|             | Min. | Max. | Unit |
|-------------|------|------|------|
| Temperature | 5    | 30   | °C   |
| Humidity    | -    | 85   | % RH |

## 6.2 Storage period (Start to count since delivery date)

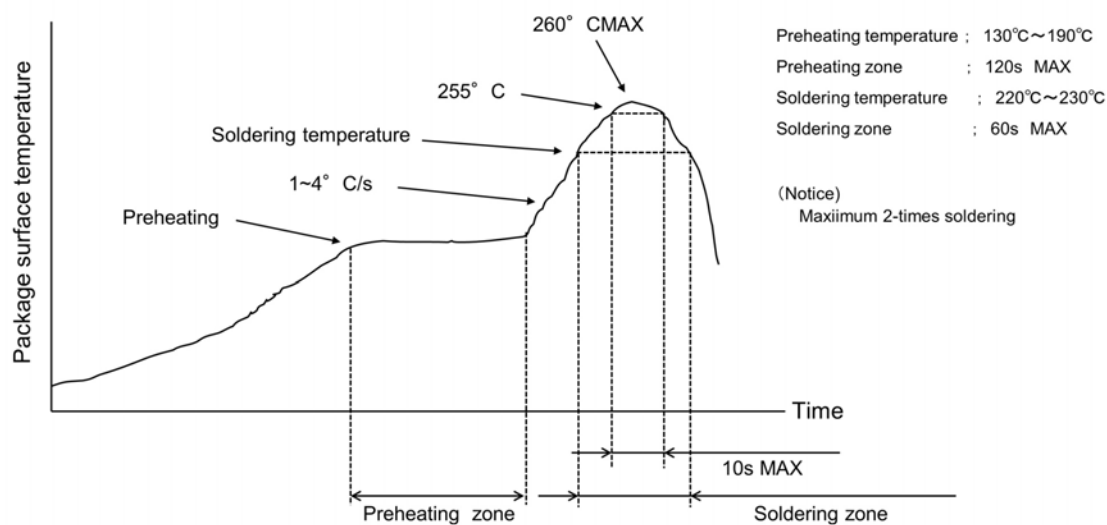
|                | Min. | Max. | Unit |
|----------------|------|------|------|
| Storage period | -    | 1    | year |

## 6.3 Drying process

Dryprocess is not required before solder mounting.

## 7. Soldering conditions

## 7.1 Recommended temperature profile for reflow



## 7.2 Recommended condition for wave soldering

|                        |   |                  |
|------------------------|---|------------------|
| Preheating temperature | : | 120 °C to 150 °C |
| Preheating time        | : | 60 s MAX         |
| Soldering temperature  | : | 260 °C ± 3 °C    |
| Soldering time         | : | 12 s MAX         |

## Notes for wave soldering

- (1) Soldering time is provided for total soldering time in case of dual wave soldering.
- (2) Do not use other soldering methods with wave soldering.
- (3) Recommend to clean the board to eliminate flux, solder waste, and other impurities for reliability, after soldering.
- (4) Optimize soldering condition to prevent solder bridging.

## 7.3 Recommended condition for solder iron

|                         |   |                |
|-------------------------|---|----------------|
| Solder iron temperature | : | 380 °C or less |
| Mounting time           | : | 4 s or less    |

## Notes for solder iron

- (1) Solder mounting time is the time per 1 lead

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